



Material Content Data Sheet



Sales Product Name				IKB20N60T		Issued		4. July 2019	
MA#				MA005342010					
Package				PG-TO263-3-2		Weight*		1559.18 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	1.102	0.07	0.07	707	707	
chip_2	inorganic material	silicon	7440-21-3	2.028	0.13	0.13	1301	1301	
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59		
	non noble metal	iron	7439-89-6	0.304	0.02		195		
wire	non noble metal	copper	7440-50-8	304.026	19.50	19.53	194991	195245	
	non noble metal	aluminium	7429-90-5	6.509	0.42	0.42	4174	4174	
encapsulation	organic material	carbon black	1333-86-4	10.251	0.66		6575		
	plastics	epoxy resin	-	112.761	7.23		72321		
leadfinish	inorganic material	silicondioxide	60676-86-0	560.390	35.93	43.82	359413	438309	
	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6193	6193	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148	
solder	non noble metal	tin	7440-31-5	0.069	0.00		44		
	noble metal	silver	7440-22-4	0.086	0.01		55		
heatspreader	non noble metal	lead	7439-92-1	3.296	0.21	0.22	2114	2213	
	inorganic material	phosphorus	7723-14-0	0.165	0.01		106		
*deviation	non noble metal	iron	7439-89-6	0.548	0.04		352		
	non noble metal	copper	7440-50-8	547.666	35.13	35.18	351252	351710	
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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